

Product Data Sheet

Product	396-DRM
Productgroup	Wave solder flux
Date	15-07-2010
Release	10.2

5	Especially made for this purpose
4	Generally qualified for this purpose
3	Generally usable, but not the best choice
2	Generally not usable for this purpose
1	Wrong choice

ISO 9454-1	2.1.3.A
IPC-ANSI-J-STD-004	ORM0
JIS Z 3197	2.1.3.N_I
No-Clean process	5
Post-solder cleaning	4
Selective Soldering	3
Pb-Free process - Ambient	5
Pb-Free process - N2	5
N2 Process - Full Tunnel	3
N2 Process - Wave Only	5
Consumer electronics	5
Med-Rel electronics	4
Hi-Rel electronics	3
1-layer, video/tv boards	5
2-layer boards	5
Multi-layer boards	5
OSP compatible	5
Ni/Au compatibel	5
Ni/Pd compatible	5
Ag compatible	5
Sn compatible	5
Foam fluxing	3
Nozzle-spray fluxing	5
Moderate preheat	3
Short contact time with solder	5
Reduces skipped joints	5
Reduces solder balling	4
Reduces bridging	5
Promotes wicking	5
Cosmetic cleanliness	4
Cosmetic cleanliness N2	4
Dull/frosty joints	2
ICCT compatible	5
Conformal coating	3

SG @ 20 °C [kg/dm3] (+/- 0.5%)	1.012
Solids content [% w/w]	4.00
Halides [Silver-Chromate Test]	Pass
Halides [Potentiometric]	Pass
Acid number [mgKOH] (+/-2.5%)	36.85
Water content [% w/w]	95.
VOC-content [% w/w]**	-
Filmformer(s)	OA
Flashpoint COC [°C]	-
Odor	None
Color	Colorless
Telcordia/Bellcore TR-NWT-000078/3	Compliant
IPC/ANSI-J-STD-005	Compliant
Test report(s)	-
ISO-9001	0043973
Certificate of Compliance	Available
SPC-data*	Auditable
Environmental Load Unit	1.29
RoHS-Compliance Certificate	Available
User's Guidelines	English
Thinner	Demi-water
Packaging	
Can (HDPE) [liter]	10
Drum (HDPE) [liter]	200
Shelf-life (Weeks)	
Storage 20 [°C]	52.
Storage 25 [°C]	26.
*Certain conditions apply.	
**Having a vapor pressure of >0.01 mm Hg @ 25 °C	
Industrial chemical product. Read MSDS before use.	